



Product End-of-Life Disassembly Instructions

Product Category: Notebooks

Marketing Name / Model
[List multiple models if applicable.]

HP EliteBook X G1a 14 inch Notebook Next Gen AI PC (ENERGY STAR)

HP ZBook Ultra G1a 14 inch Mobile Workstation PC (ENERGY STAR)

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP Inc. products to remove components and materials requiring selective treatment, as defined by EU directive 2012/19/EC, Waste Electrical and Electronic Equipment (WEEE).

NOTE: Recyclers should sort plastic materials into resin streams for recycling based on the ISO 11469 plastic marking code on the plastic part. For any questions on plastic marking or identification of location of parts or components requiring selective treatment, please contact [HP's Sustainability Contact](#).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment. An "X" in the list of components and parts indicates the product contains the component or part requiring selective treatment

Item Description	Components and parts requiring selective treatments	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA) with a surface greater than 10 sq cm	<input checked="" type="checkbox"/> Main board (MB) PCB <input checked="" type="checkbox"/> Solid state drive (SSD) PCB <input checked="" type="checkbox"/> Wireless WAN module (WWAN) PCB <input checked="" type="checkbox"/> Touch module PCB <input type="checkbox"/> Power supply PCB <input type="checkbox"/> External Keyboard (KB) <input type="checkbox"/> External Mouse <input type="checkbox"/> Others: _____ IO board PCB _____	4
Batteries, excluding Li-Ion batteries. This includes standard alkaline, coin or button style batteries	<input type="checkbox"/> RTC/CMOS battery <input checked="" type="checkbox"/> Others: NA	0
Li-Ion batteries. Includes all Li-Ion batteries if more than one is provided with the product (such as a detachable notebook keyboard battery, etc.)	Li-ion battery(ies) are attached to the product by: <input checked="" type="checkbox"/> screws <input type="checkbox"/> snaps <input type="checkbox"/> adhesive <input type="checkbox"/> other. Explain _____	5

Item Description	Components and parts requiring selective treatments	Quantity of items included in product
Mercury-containing components. For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	NA	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm. Includes background illuminated displays with gas discharge lamps	<input checked="" type="checkbox"/> Panel LCD	1
Cathode Ray Tubes (CRT)	NA	0
Capacitors / condensers (Containing PCB/PCT)	NA	0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height	<input type="checkbox"/> Power Supply capacitor(s) or condenser(s)	0
External electrical cables and cords	<input checked="" type="checkbox"/> AC power cord <input type="checkbox"/> Audio, video or data cables <input type="checkbox"/> Other: _____	1
Gas Discharge Lamps	NA	0
Plastics containing Brominated Flame Retardants (not including external electrical cables and cords, PCBs or PCAs already listed as a separate item above)	NA	0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner. Include the cartridges, print heads, tubes, vent chambers, and service stations.	NA	0
Components and waste containing asbestos	NA	0
Components, parts and materials containing refractory ceramic fibers	NA	0
Components, parts and materials containing radioactive substances	NA	0
Components containing chlorofluorocarbons (CFC), hydrochlorofluorocarbons (HCFC) or hydrofluorocarbons (HFC), hydrocarbons (HC)	NA	0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Screwdriver	Philip #0
Screwdriver	Torx T8
Heatgun	N/A
Suction cup	N/A

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment including the required steps to remove the external enclosure.

1. Remove D cover
2. Remove Battery
3. Remove SSD card
4. Remove-Thermal
5. Remove Fan
6. Remove Hinge screw
7. Remove contact cable
8. Remove MB
9. Remove IO board
10. Remove C cover
11. Remove Panel
12. Remove Hinge
13. Remove camera moudle
14. Remove Touch board

3.2 Location of components requiring selective treatment. The photos and/or graphics below identify the location of the parts or components requiring selective treatment within the main unit. For End-of-Life product disassembly instructions of external accessories including external power supply (EPS), external keyboard (KB) external mouse and external cables and cords, refer to the following URL: [End-of-Life Product Disassembly Instructions \(hp.com\)](https://www.hp.com/End-of-Life-Product-Disassembly-Instructions)

Please refer the attached file.	
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Step 1 Remove D-cover

Tooling : #0 screw driver
Remove 4pcs screw



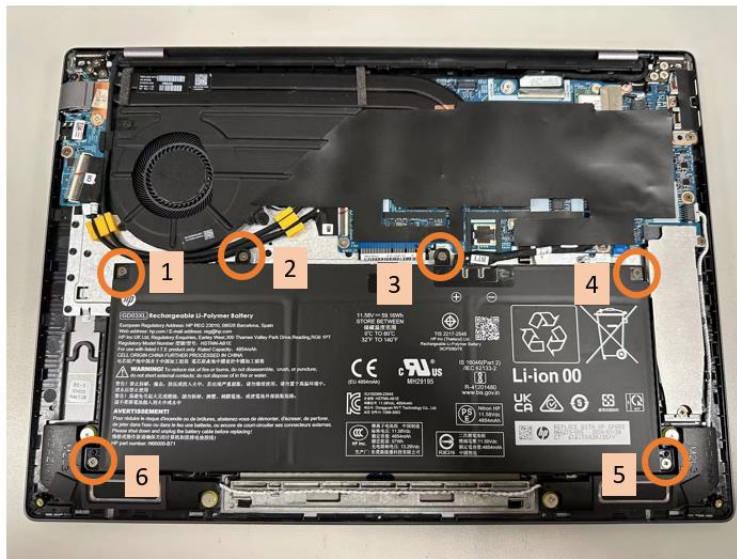
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Step 2 Remove Battery

Tooling : #0 screw driver
Remove 6pcs screw



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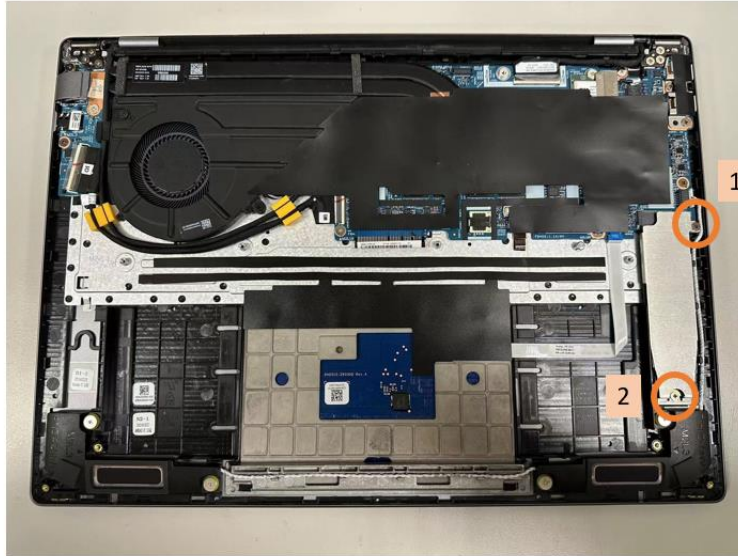
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EL-MF877-00
Template Revision D

last updated May-2022

Step 3 Remove SSD Card

Tooling : #0 screw driver
Remove 2pcs screw



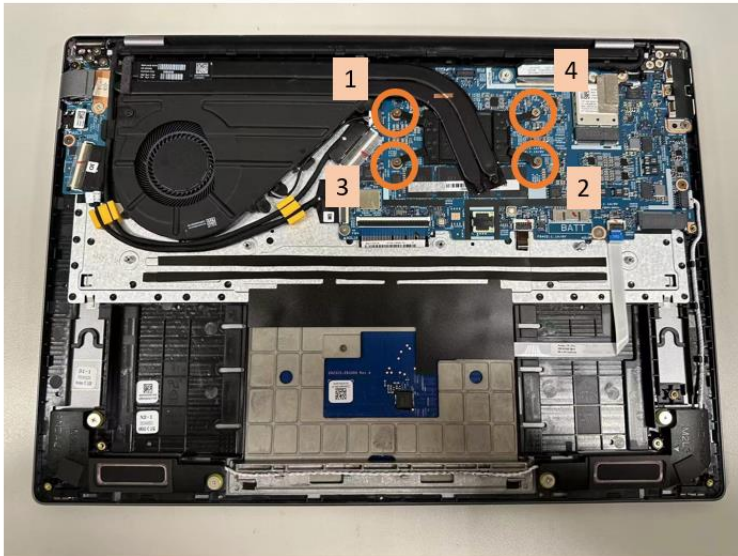
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Step 4 Remove Thermal

Tooling : #0 screw driver
Remove 4pcs screw



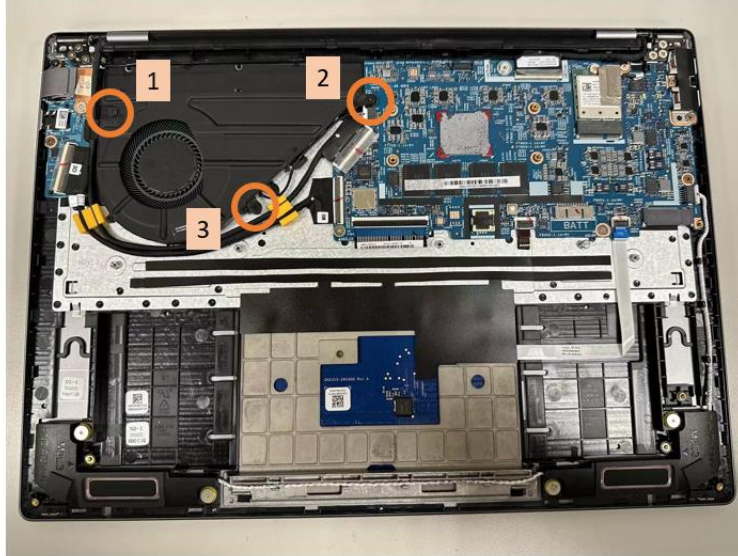
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Step 5 Remove Fan

Tooling : #0 screw driver
Remove 3pcs screw



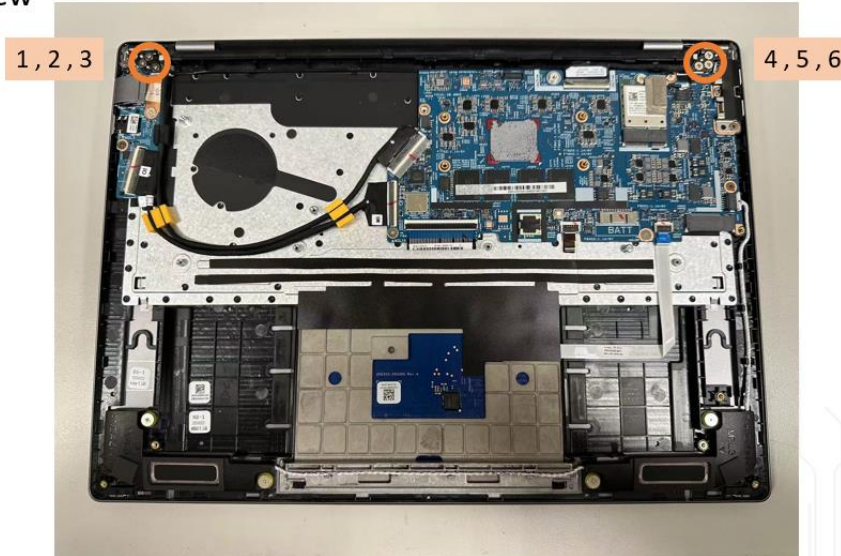
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Step 6 Remove Hinge Screw

Tooling : #0 screw driver
Remove 6pcs screw



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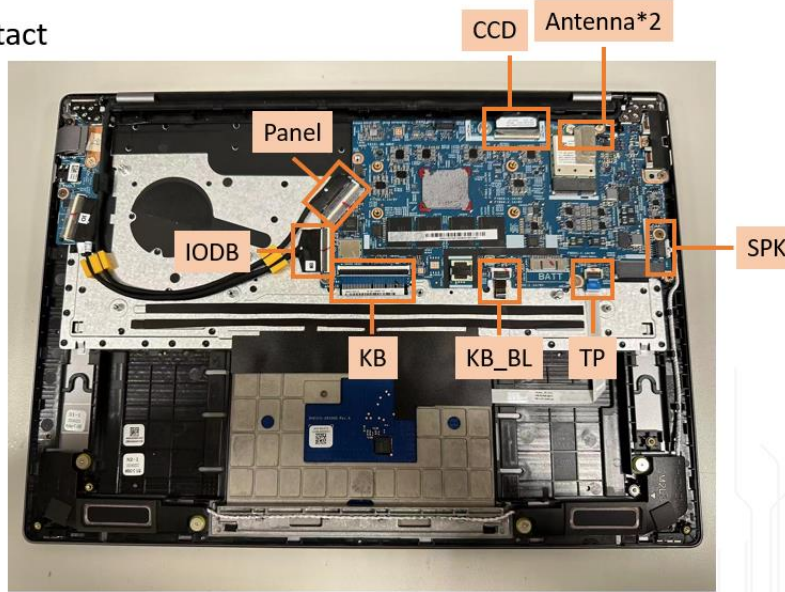
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Step 7 Remove Contact Cable

Tooling : N/A

Remove All cable contact



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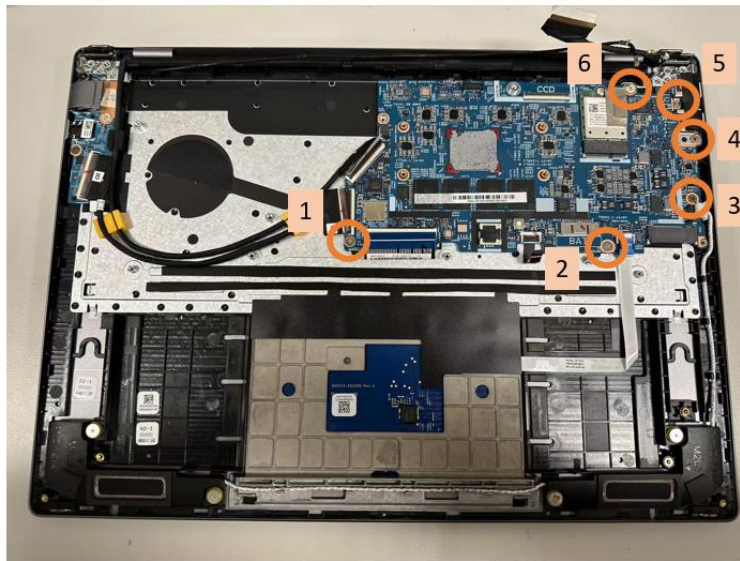
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Step 8 Remove MB

Tooling : #0 screw driver

Remove 6pcs screw



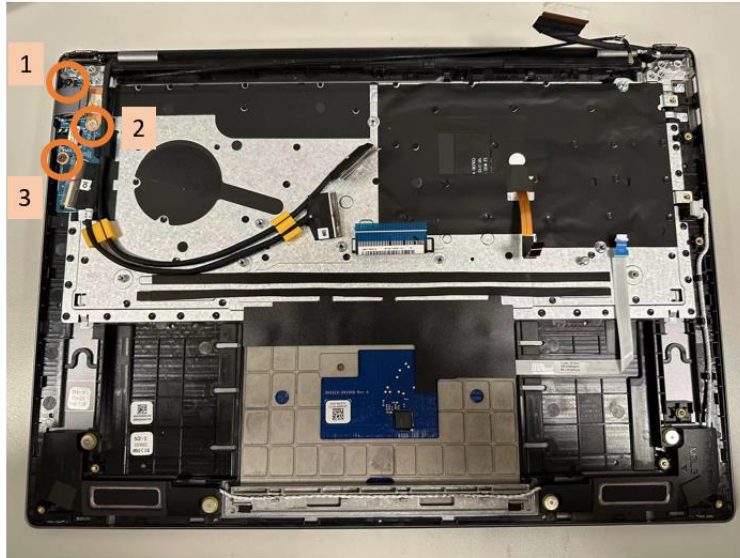
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Step 9 Remove IO Board

Tooling : #0 screw driver
Remove 3pcs screw



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Step 10 Remove C-cover

Tooling : N/A
Remove C cover



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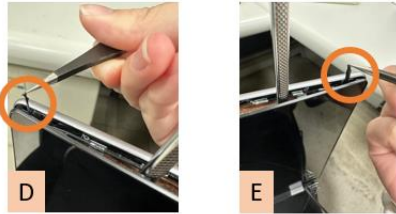
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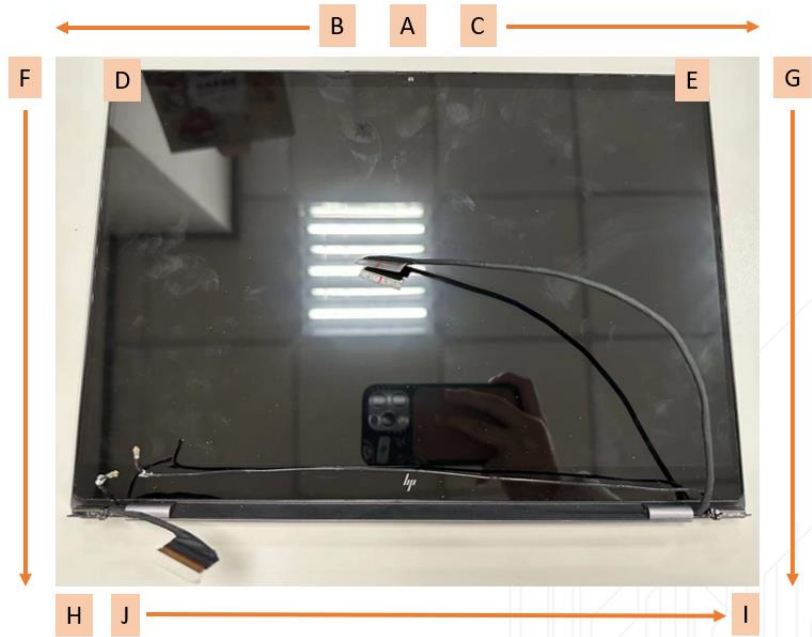
Step 11 Remove Panel

Tooling : N/A

- 1. Remove Bezel Hooks Steps :
A → B → C
- 2. Remove 2pcs Pull Adhesive :
D → E



- 3. Remove Bezel Hooks Steps :
F → G → H → I → J



11

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Step 12 Remove Hinge

Tooling : #0 screw driver

Remove 10pcs screw



12

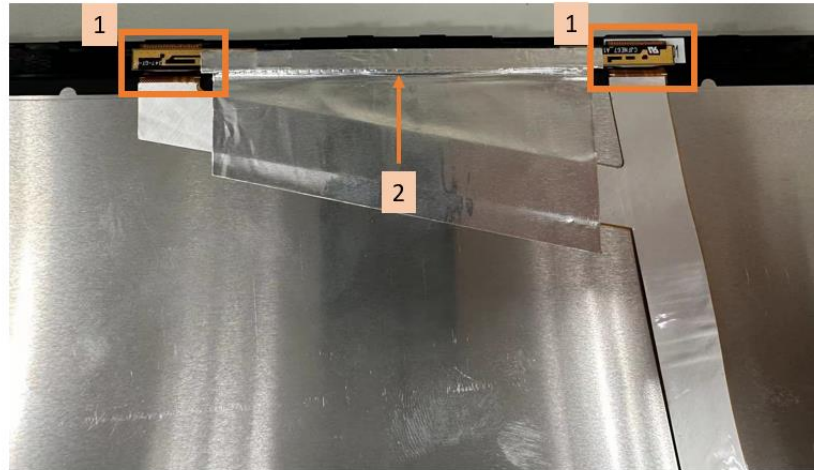
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Step 13 Remove Camera Module

Tooling : N/A

1. Remove Camera Module Cable
2. Remove Camera Module (Assembly for Adhesive)



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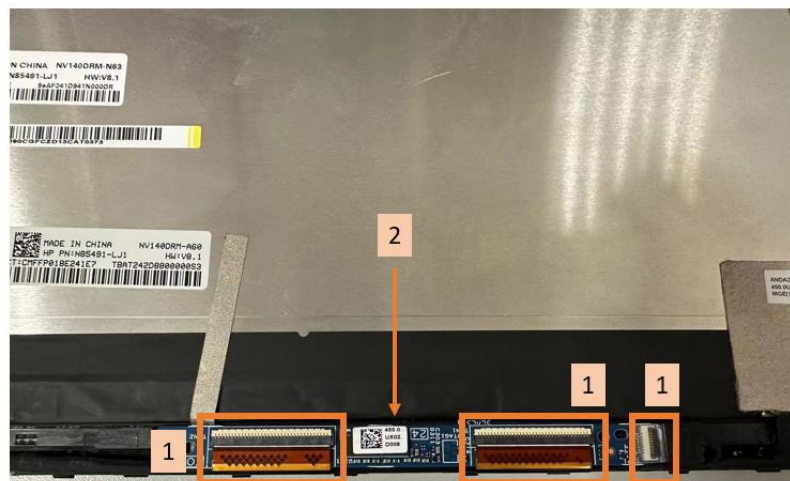
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Step 14 Remove Touch Board

Tooling : N/A

1. Remove Touch Board Cable
2. Remove Touch Board (Assembly for Adhesive)



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14

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